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(54) **FIXING STRUCTURE FOR A HEAT DISSIPATION DEVICE**(52) **U.S. Cl.**CPC **H05K 7/2049** (2013.01); **F28F 9/007** (2013.01); **F28F 2275/20** (2013.01)(71) Applicant: **Cooler Master Co., Ltd.**, New Taipei City (TW)

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ABSTRACT(72) Inventors: **Jen-Chih Cheng**, New Taipei City (TW); **Shui-Fa Tsai**, New Taipei City (TW)

A fixing structure of a heat dissipation device is provided. The fixing structure has a plate portion and at least one fixing set. The plate portion forms an opening and at least one groove. The opening and the groove form through the plate portion. The opening is configured to fix a heat dissipation assembly. The fixing set is mounted through the groove and can be moved in an extending direction of the groove and a direction perpendicular to the plate portion. The shape of the groove may correspond to various locations of the fixing hole on the various substrates. The fixing set can be moved in the groove to align various fixing holes of the substrate. In other words, with the movable fixing sets, the fixing structure can be mounted on various substrates or correspond to the electronic component in various shapes and dimensions.

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